DATASHEET

Phenom ParticleX Steel

Multipurpose desktop SEM enabling high-quality steel manufacturing







SEM image of non-metallic inclusion in steel.

The control over non-metallic inclusions during the steel making process is a key skill for the efficient production of modern steels demanded by today's customers. To be competitive in today's steel making requires knowledge of the many parameters that control the formation of the non-metallic inclusions in the steel. Timely and accurate data are the prerequisites for gaining the insight required for high-value steel making.

In addition to providing high-quality SEM analysis, the Thermo Scientific[™] Phenom[™] ParticleX Steel Desktop SEM is also designed to perform a number of specific functions. These include particle analysis of metal powders at the microscale for the additive industry, confirmation components fulfill technical cleanliness requirements, and analysis of inclusions in steel. All have now been made possible in-house and on your desktop.

Phenom ParticleX Desktop SEM: general SEM usage

The Phenom ParticleX Desktop SEM features a chamber that includes an accurate and fast motorized stage that allows analysis of samples of up to 100x100 mm. In spite of this larger sample size, a proprietary loading shuttle keeps the vent/load cycle to an industry-leading sample loading time of 40 seconds or less. In practice, this improves the throughput factors more than other SEM systems.

The user interface is based on the proven ease-of-use technology applied in our successful Phenom desktop SEM products. The interface enables both existing and new users to quickly become familiar with the system with a minimum of training.



SEM image of Zinc-Phosphate on sheet metal.

The standard detector in the Phenom ParticleX Desktop SEM is a four-segment backscattered electron detector (BSD) that yields sharp images and provides chemical contrast information together with a fully integrated energy dispersive X-ray (EDX) system for elemental analysis. A secondary electron detector (SED) for surface sensitive imaging is optional.

Elemental analysis is provided by EDX technology, which allows you to analyze the chemical composition of your samples. Detailed chemical composition can be obtained from a micro volume via spot analysis. Elemental distribution can be visualized with the elemental mapping option.

Elemental mapping and line scan

It is simply click-and-go to work with the elemental mapping and line scan functionality of the Phenom ParticleX Desktop SEM. The elemental mapping functionality visualizes the distribution of elements throughout the sample, and selected elements can be mapped at a user-specified pixel resolution and acquisition time. The real-time mapping algorithm shows live build-up of the selected elements. The line scan functionality shows the quantified element distribution in a line plot. This is especially useful for coatings, paints and other applications with multiple layers for analyzing edges, coatings, cross sections and more. Results of both the elemental mapping and line scan functionality can be easily exported by using an automated report template.



User interface ParticleX software.

Secondary electron detector

A secondary electron detector (SED) is optionally available on the Phenom ParticleX Desktop SEM. The SED collects low-energy electrons from the top surface layer of the sample, making it the perfect choice to reveal detailed sample surface information. The SED can be of great use for applications where topography and morphology are important. This is often the case when studying microstructures, fibers or particles.

Phenom ParticleX Desktop SEM: analyzing inclusions in steel

The Phenom ParticleX Desktop SEM for steel inclusion analysis is a versatile and easy to use SEM/EDX instrument for failure analysis and inclusion analysis. It is a proven solution for monitoring non-metallic inclusions in steel. The Phenom ParticleX Desktop SEM for steel inclusion analysis measures various size and shape parameters as well as chemistry of each individual inclusion.

The supplied recipes allow you to quickly get started with the analysis of Al-killed, Si-killed and Ca-treated steels. These recipes can be applied while specific parameters like inclusion size range, chemical classification rules, area of interest and stop criteria can be set for your specific application.



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Elemental mapping to analyze complex multiphase inclusions.

Once the data is acquired, a report can be generated according to user defined reports. Such customized reports can contain ternary plots, histograms, and inclusion density calculations to quickly visualize your results and compare your samples. After the automated analysis, every inclusion can be revisited manually for further analysis.



Plot inclusion size distributions to gain insight into relationships between inclusion chemistry and size.

Plot ternary diagrams to gain insight into inclusion chemistry.

Imaging specifications		EDX s	
Imaging modes		Hardw	
Light optical	Magnification range: 3–16x		
Electron optical	Magnification range: 160–200,000x	Detect	
	• Digital zoom max. 12x	Detect	
Illumination		V	
Light optical	Bright field / dark field modes	∧-ray v	
Electron optical	 Long lifetime thermionic source (CeB₆) 	Energy	
	Multiple beam currents	Proces	
	 Default: 5 kV, 10 kV and 15 kV 	Max. ir	
Acceleration voltages -	Advanced mode: adjustable	Hardw	
	range between 4.8 kV and 20.5 kV imaging and	Sonwa	
	analysis mode		
Vacuum levels	Low - medium - high	 Auto Itera 	
Resolution	<10 nm	• Con	
Acceleration voltages		• Exp	
analysis	15 KV	Repor	
Detector		Docx f	
	 Backscattered electron detector 	Eleme	
Standard	 Energy dispersive spectroscopy detector 	Eleme	
Optional	Secondary electron detector	Elemer	
Digital image detection		Backs	
Light optical	Proprietary high-resolution color navigation camera, single shot	Selecte	
	High-sensitivity backscattered	- Mappir	
Electron optical	electron detector (compositional	Pixel d	
Imaga formata	and topographical modes)	Line S	
		Line Sc	
Image resolution options		Points	
960x600 1920x1200 3840	(2400-7680x4800 pixels	Dener	
Data storage		Dooy f	
USB flash drive. Network. Workstation			
Sample stage		Detect	
Computer-controlled motoriz	red X and Y		
Sample size			
 Max. 100x100 mm (up to 1 	36 x 12 mm pin stubs)		
• Max. 40 mm height (optio	nal up to 65 mm)		
Scan area			
• 100x100 mm			
Sample loading time			
Light optical	<5 s		
Electron optical	<60 s		

	Hardware			
		• Silicon drift detector (SDD)		
	Detector type	Thermoelectrically cooled (LN ₂ free)		
	Detector active area	25 mm ²		
	X-ray window	Ultra thin silicon nitride (Si_3N_4) window allowing detection of elements B to Am		
	Energy resolution	Mn Kα ≤132 eV		
	Processing capabilities	Multi-channel analyzer with 2048 channels at 10 eV/ch		
	Max. input count rate	300,000 cps		
	Hardware integration	Fully embedded		
Software				
 Integrated column and stage control Auto-peak ID Iterative strip peak deconvolution 				
Confidence of analysis indicator				
Export functions: CSV, JPG, TIFF, FLID, FMSA				
Report				
	Docx format			
	Elemental Mapping and Lin	- Coop op oifie stiens		
Elemental Mapping				
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	Elemental Mapping Element selection Backscatter image and mix Selected area Mapping resolution range Pixel dwell time range Line Scan	10 individual user-specified maps, plus backscatter image and mix-image x-range Any size, rectangular 16x16–1024x1024 pixels 1 - 250 ms		
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System specifications

Dimensions and weight

	316(w) x 587(d) x 625(h) mm,
Imaging module	75 ka
	75 Kg
	$145(w) \ge 220(d) \ge 213(b) mm$
Diaphragm vacuum pump	
	4.5 Kg
	$156(w) \times 300(d) \times 74(b)$ mm
Power supply	100(w) × 000(u) × 7 +(n) mm,
11.5	3 kg
	$531.5(w) \times 515.4(h) \times 250(d)$ mm
Monitor	001.0(w) × 010.4(l) × 200(d) 1111,
	6.7 kg
	$169(w) \times 456(d) \times 432(b) mm$
Workstation	100(w) X 400(d) X 402(h) hint,
	15 kg
Bequirements	
hoquironito	
Ambient conditions	
Temperature	15°C ~ 30°C (59°E ~ 86°E)
iomporataro	

Humidity	20% < RH < 80%
Power	Single phase AC 100 - 240 Volt 50/60 Hz, 300 W (max.)

Recommended table size

150x75 cm, load rating of 150 kg

Workstation Specifications

- Lenovo workstation
- i5-9500 (6 cores)
- 16 Gb RAM
- 512 Gb SSD
- Keyboard, mouse
- Microsoft Windows® 10

thermo scientific

Notes	

Find out more at thermofisher.com/phenom-particle-x-steel

